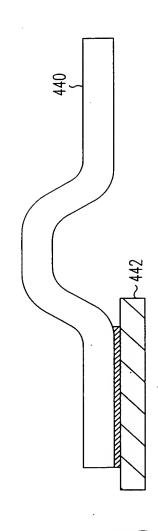


FIG. 1A (PRIOR ART)

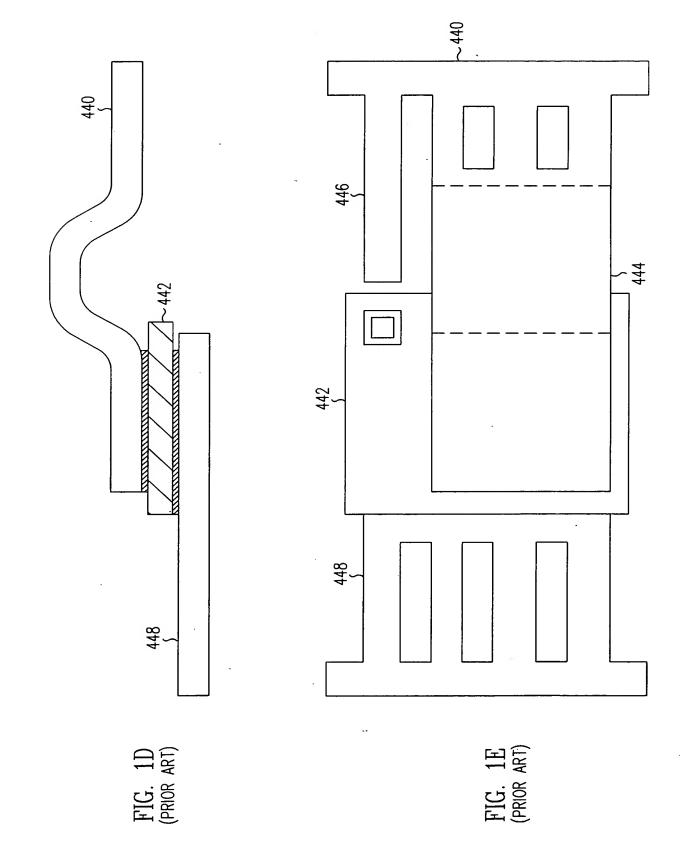
2/60

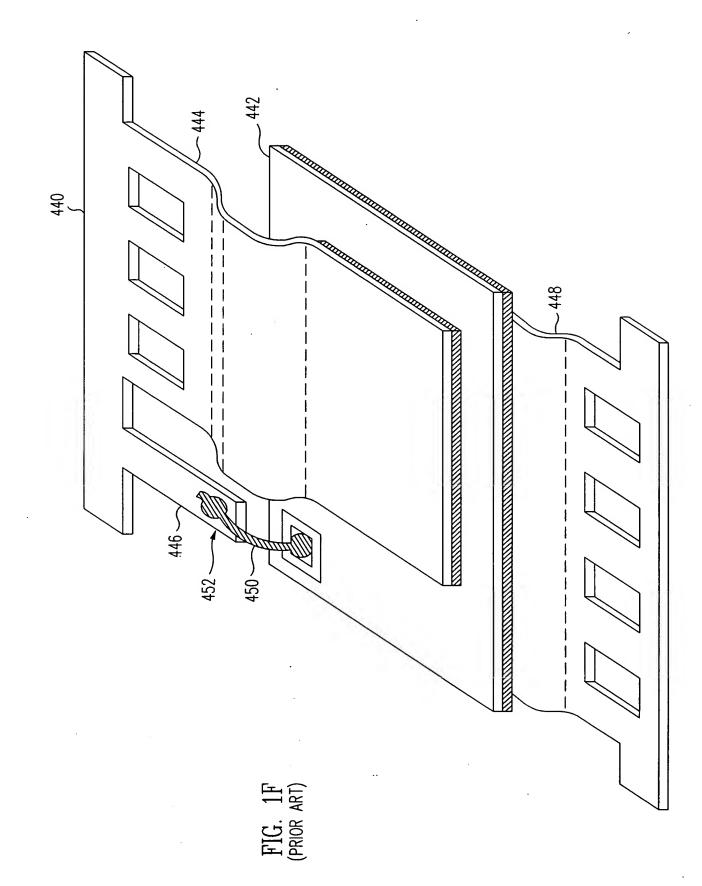


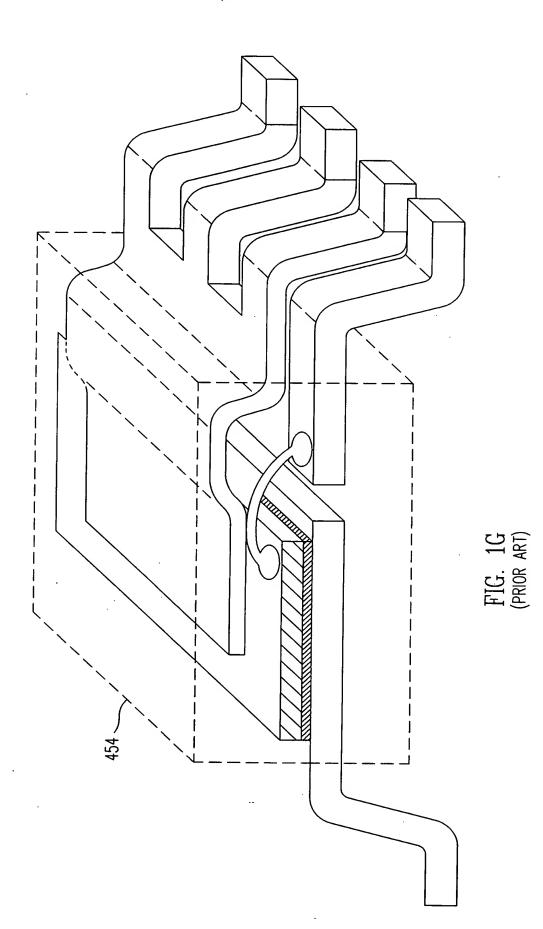
444 442 FIG. 1C (PRIOR ART)

FIG. 1B (PRIOR ART)

3/60







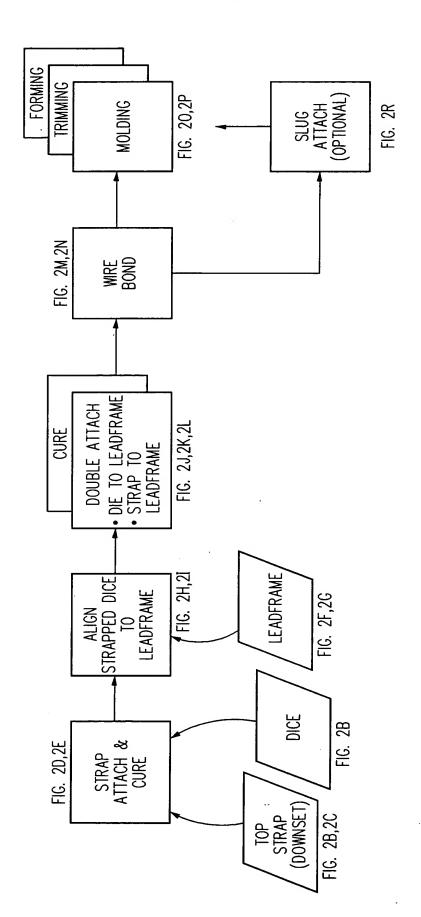
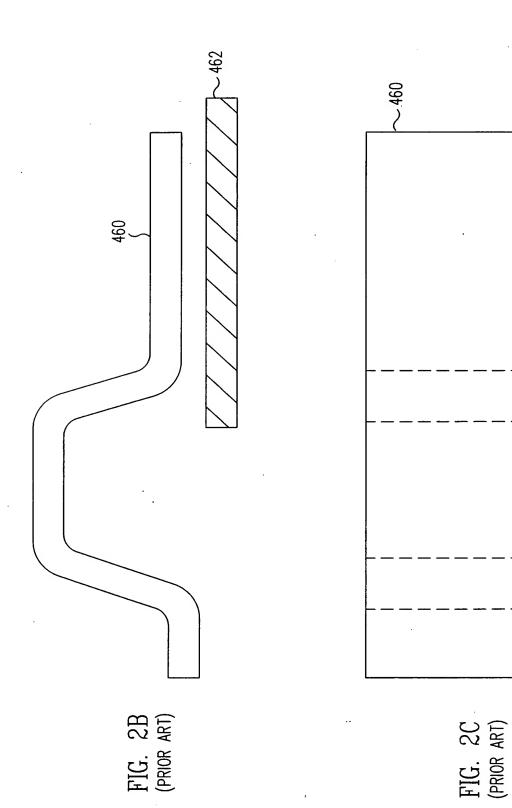
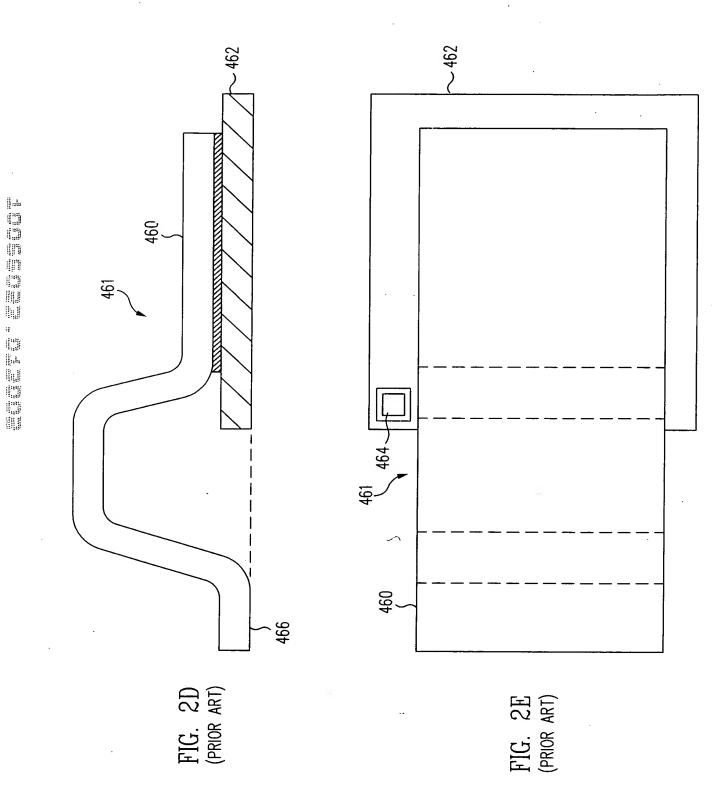


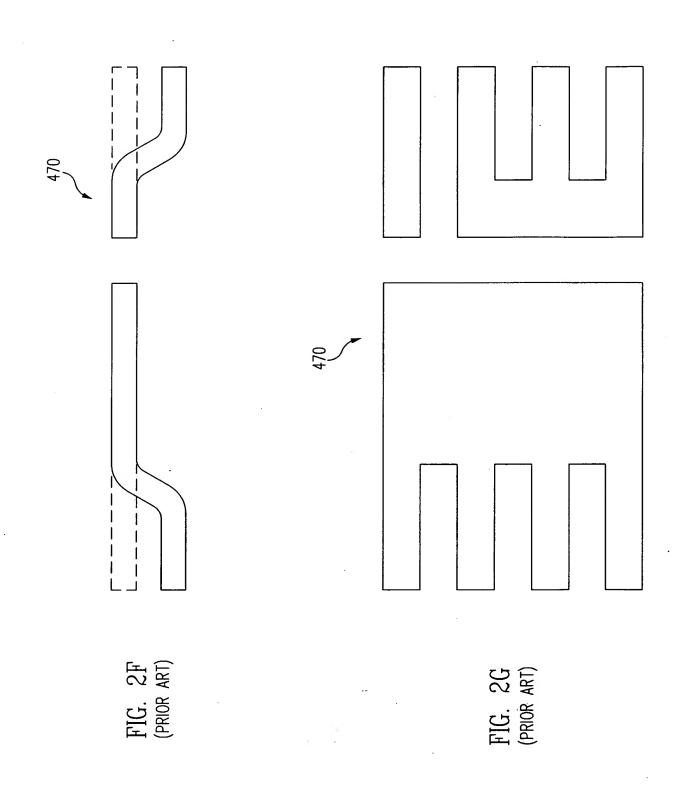
FIG. 2A (PRIOR ART)

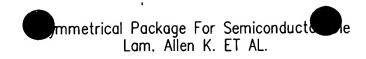


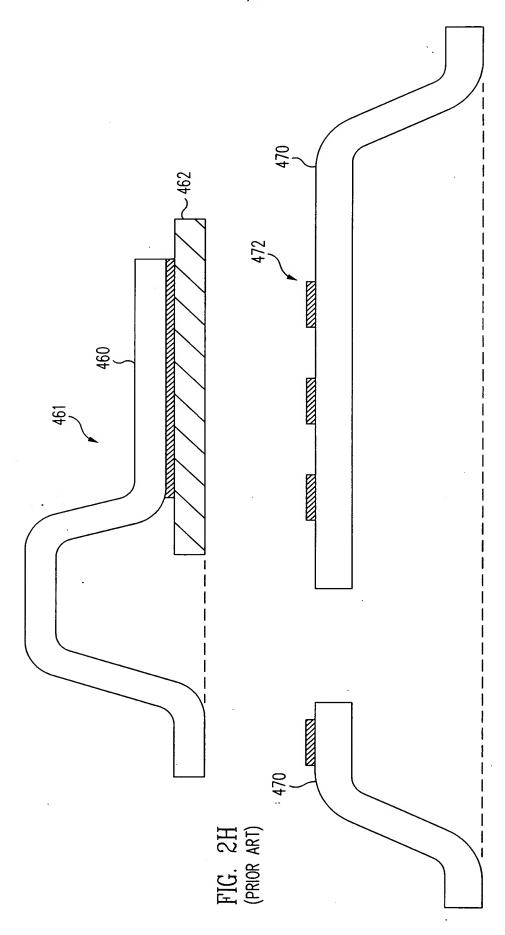




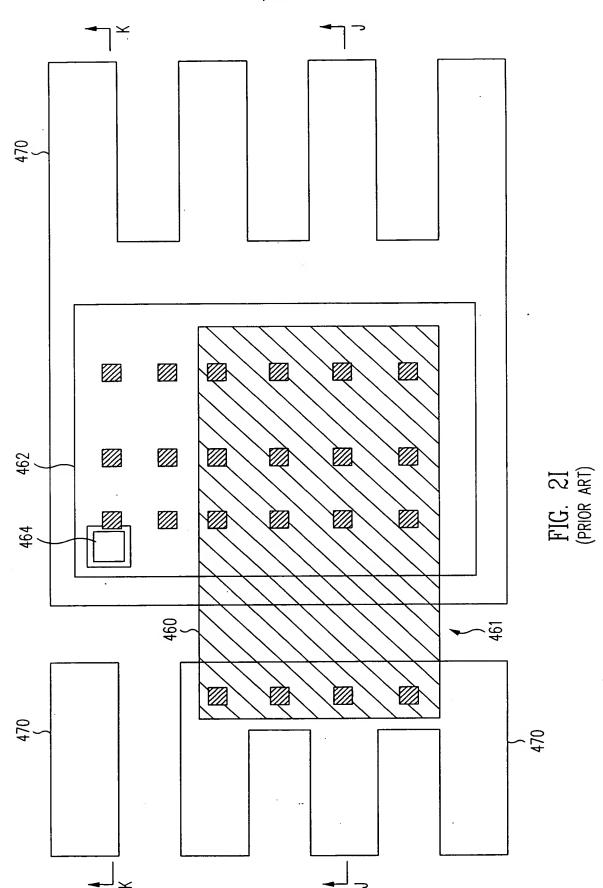
9/60







nmetrical Package For Semiconductor Lam, Allen K. ET AL.



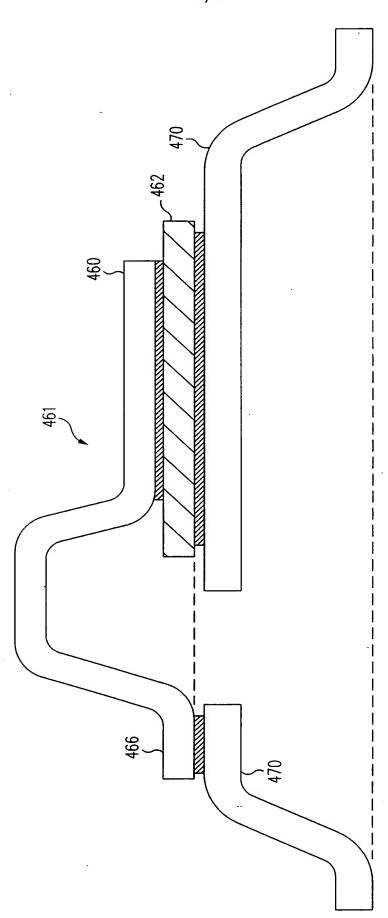


FIG. 2J (PRIOR ART)

hmetrical Package For Semiconductor Lam, Allen K. ET AL.

13/60

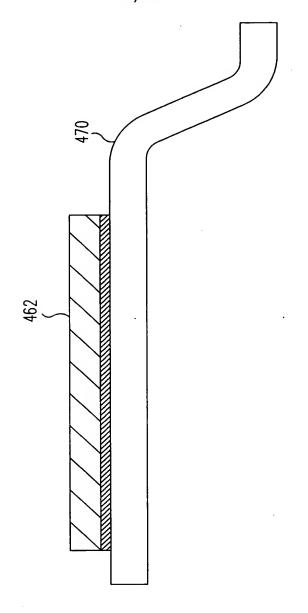
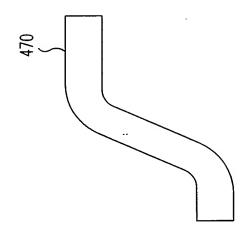
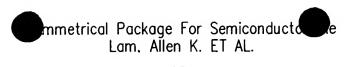


FIG. 2K (PRIOR ART)





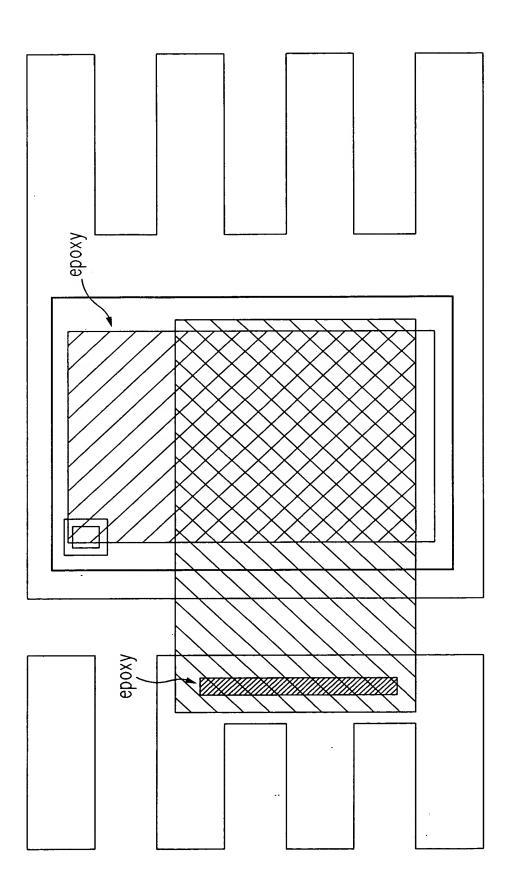


FIG. 2L (PRIOR ART)

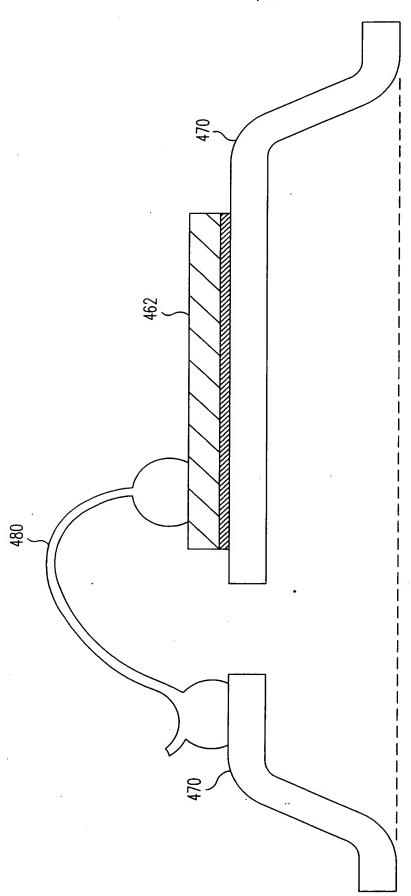


FIG. 2M (PRIOR ART)



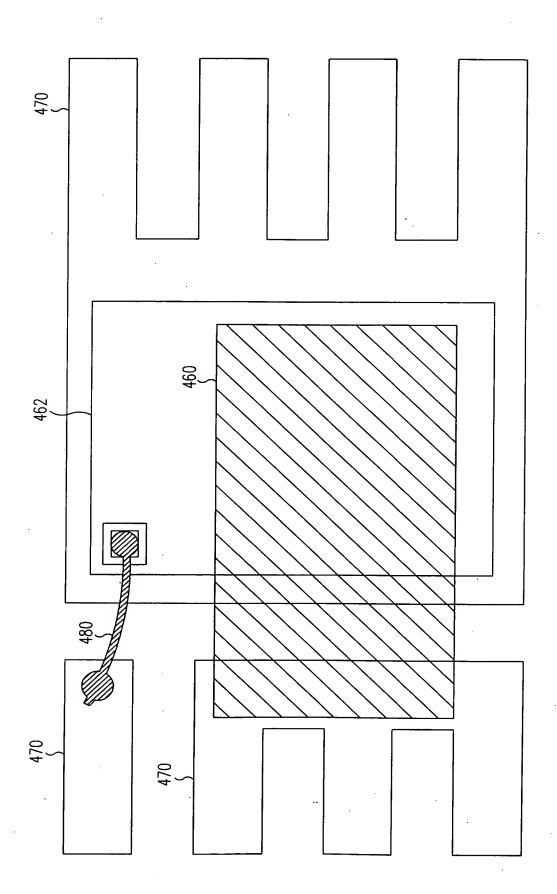


FIG. 2N (PRIOR ART)

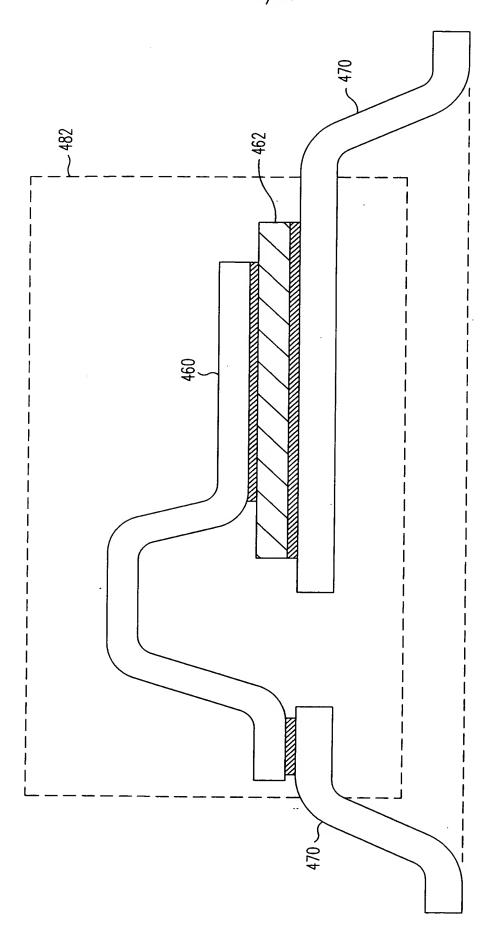
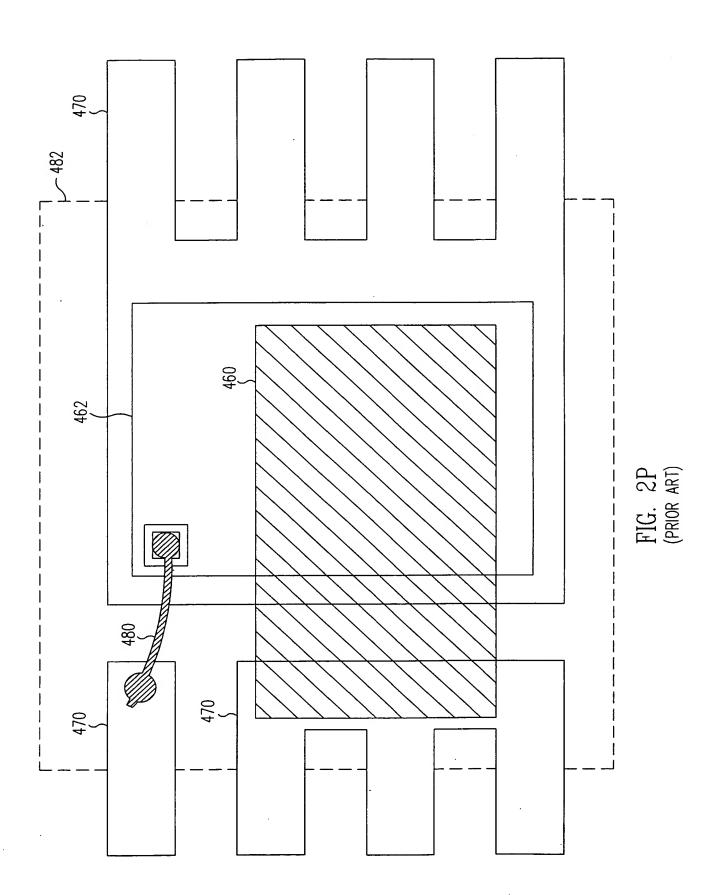


FIG. 20 (PRIOR ART)





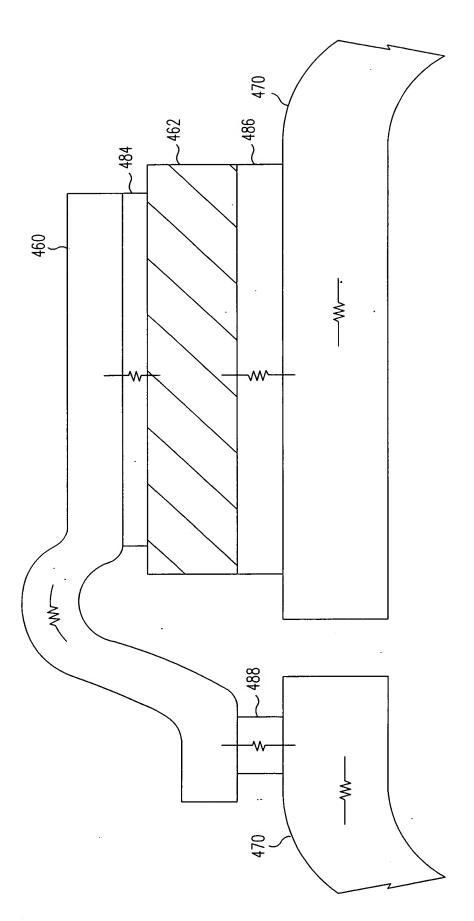
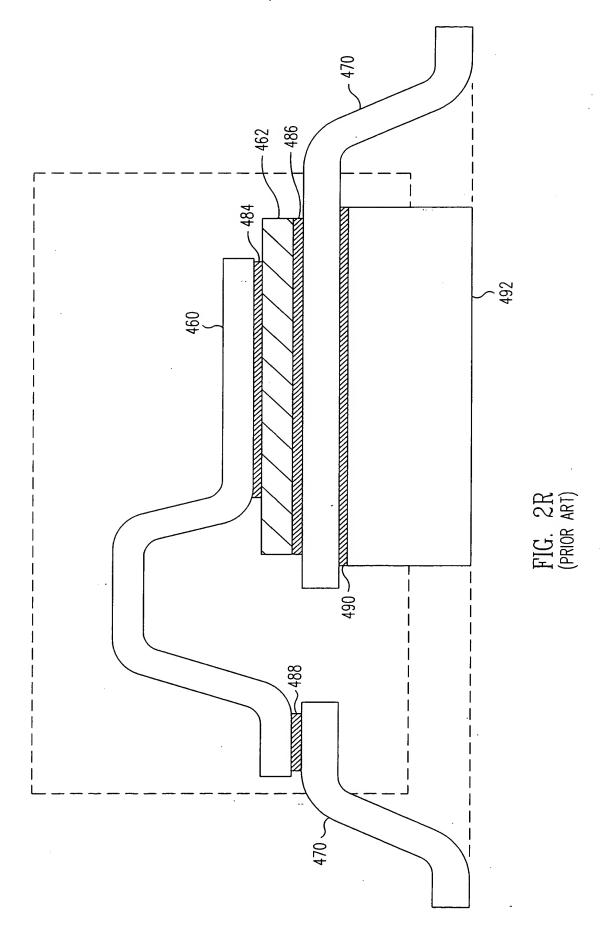
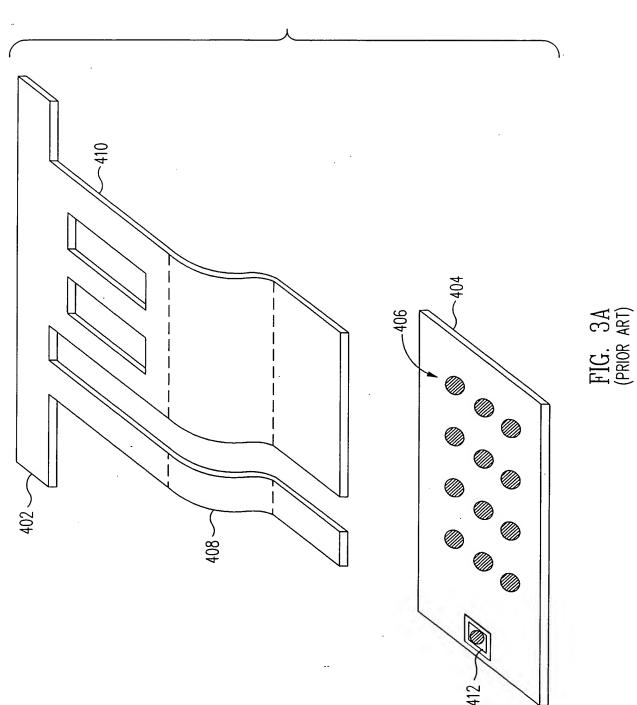


FIG. 2Q (PRIOR ART)



. 21/60



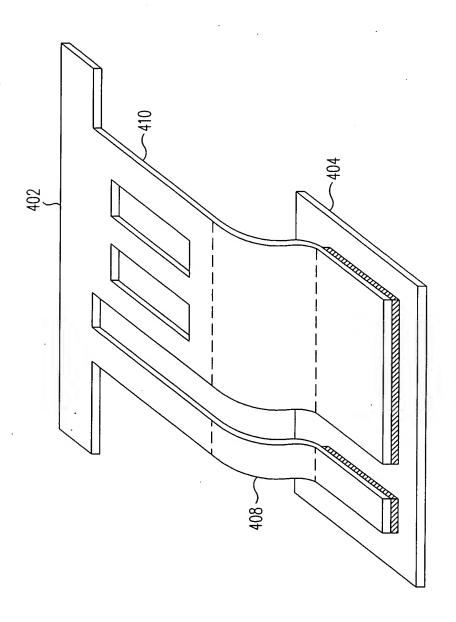


FIG. 31 (PRIOR ARI

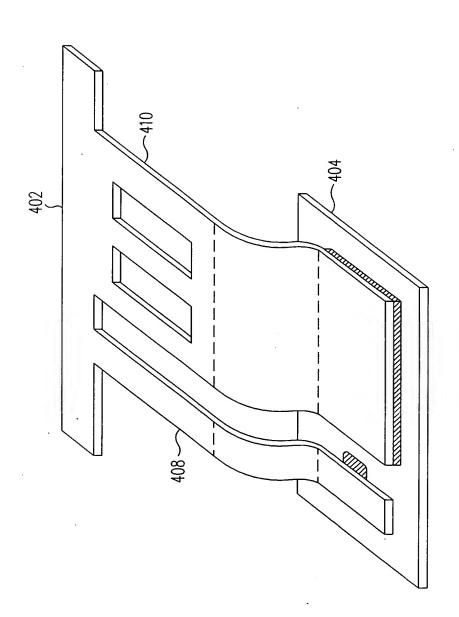
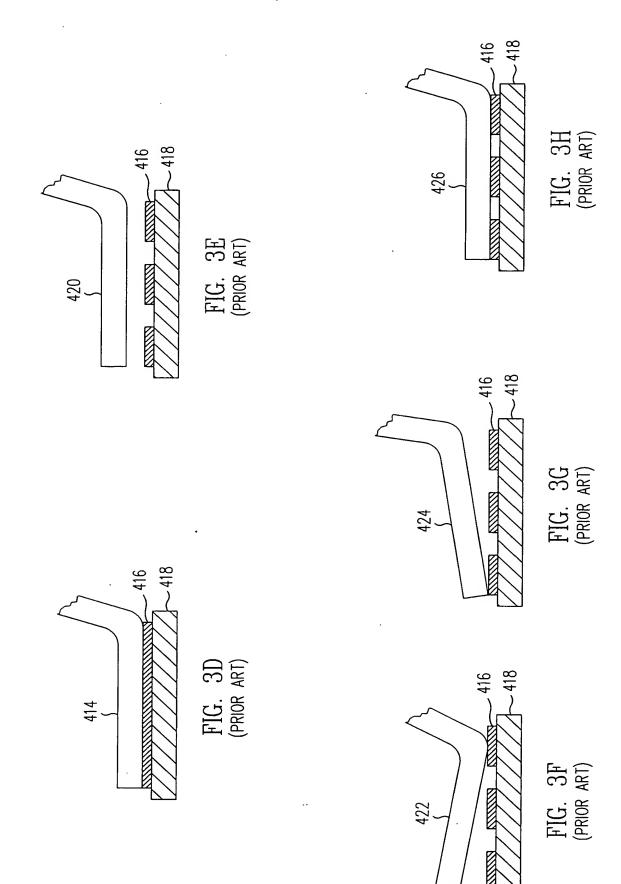
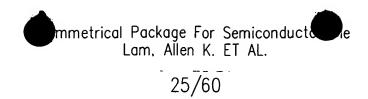
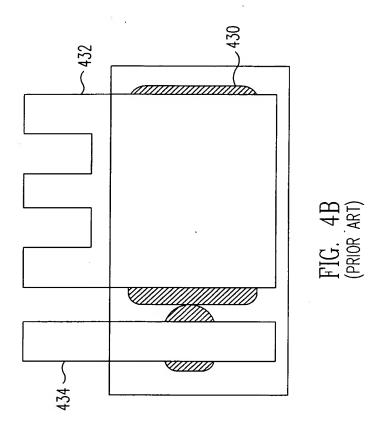


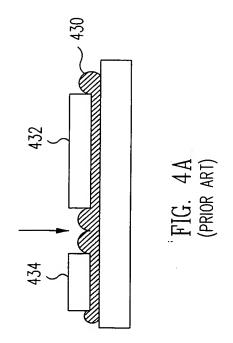
FIG. 3C (PRIOR ART)











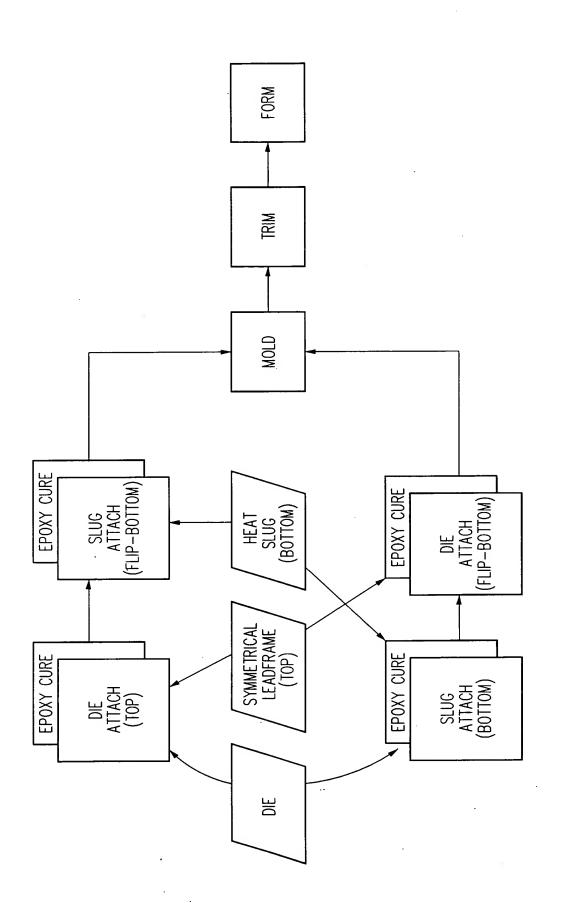
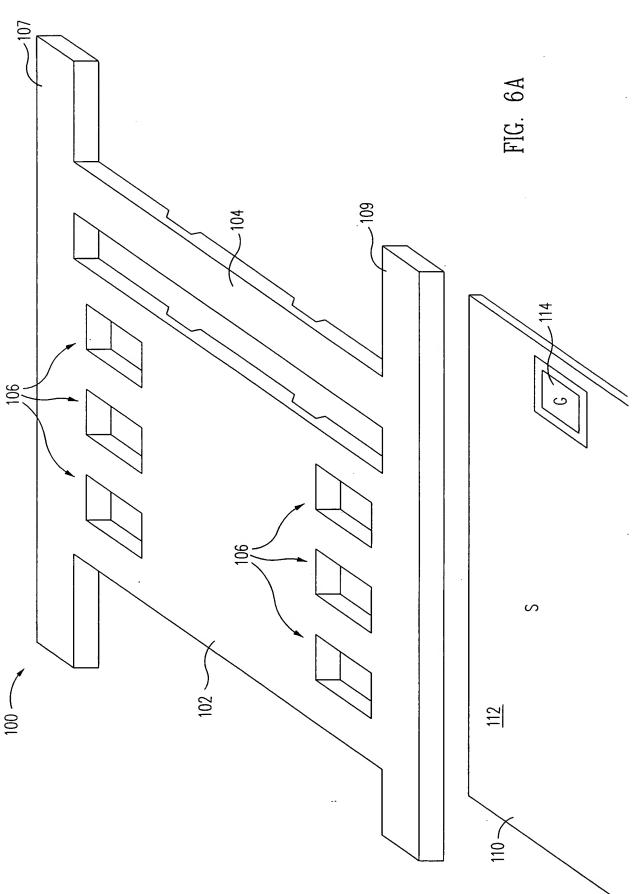
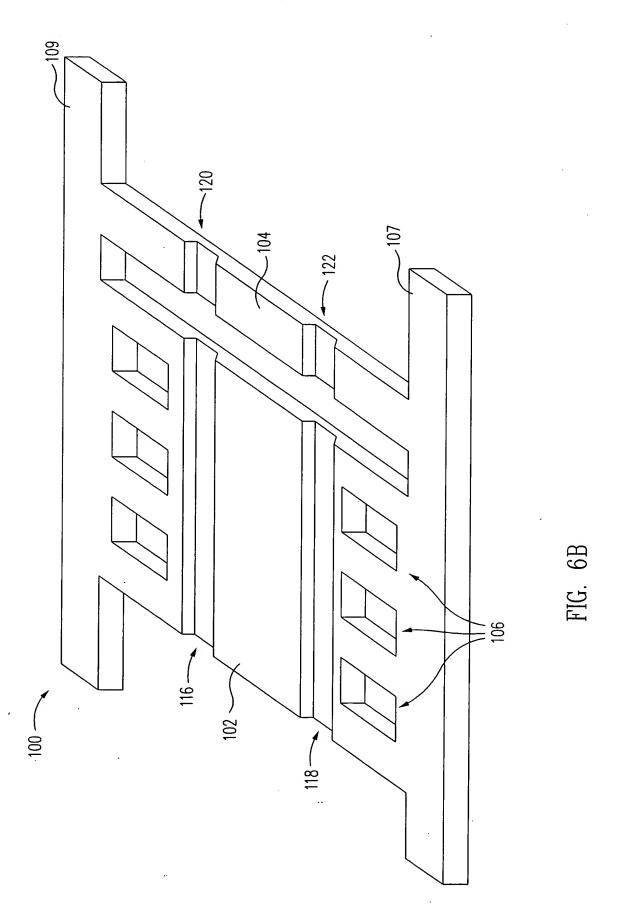


FIG. 5



28/60



29/60

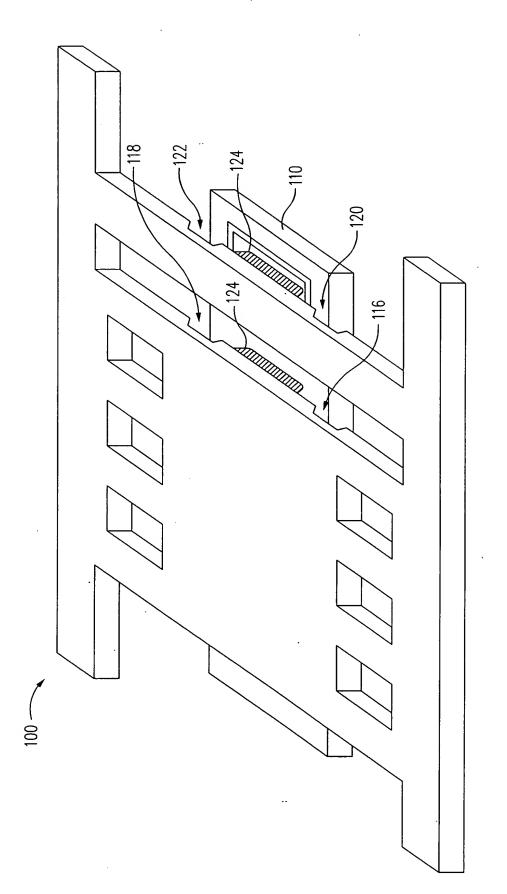
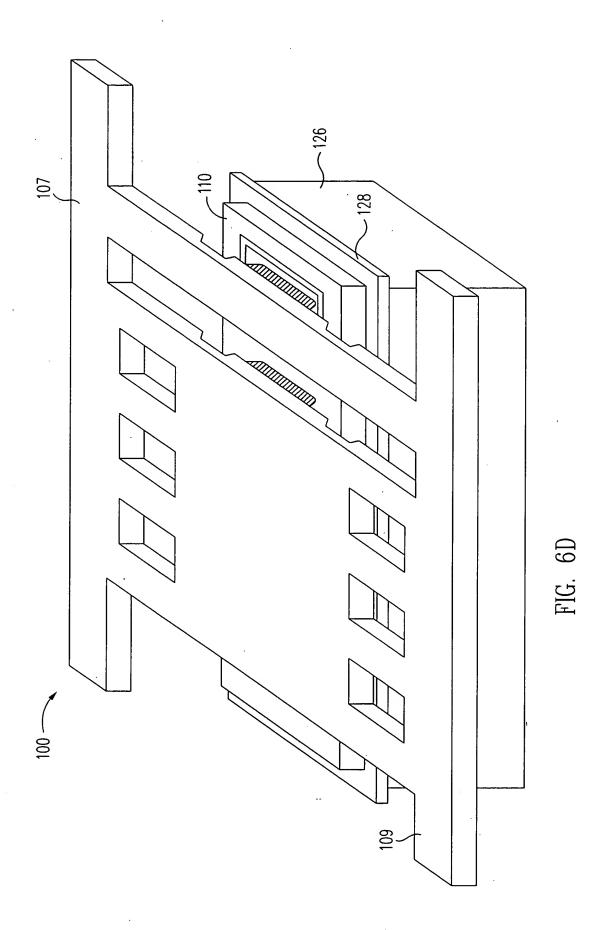


FIG. 6



31/60 132A 126 STORING THE REAL PROPERTY OF THE PARTY OF TH 130C 130B 130F 130A 100 130E 130D

32/60

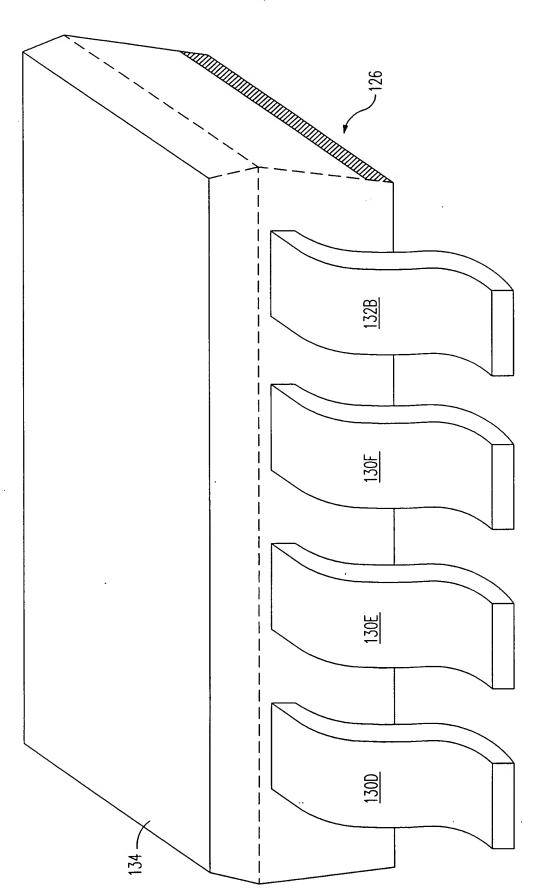


FIG. 6F

33/60

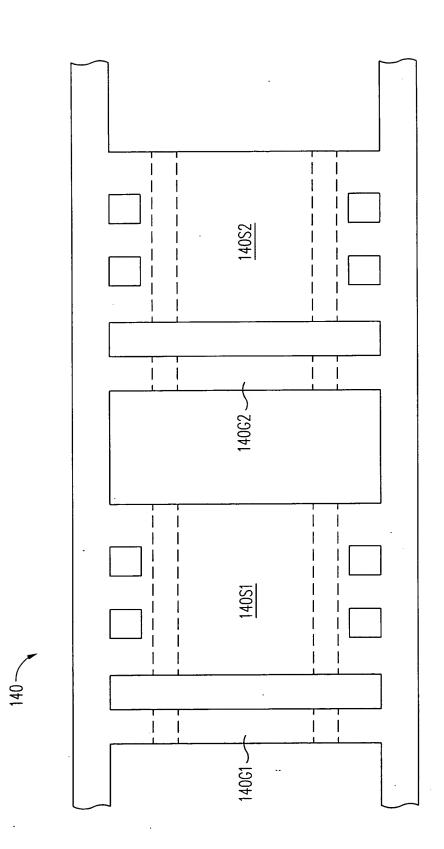


FIG. 7

34/60

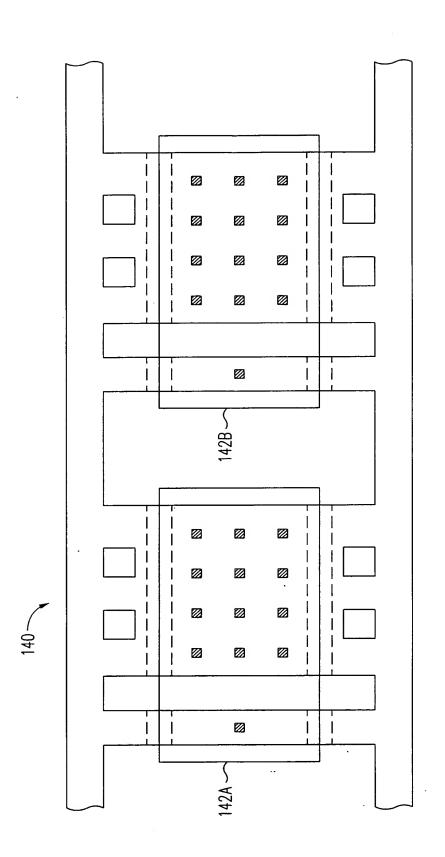
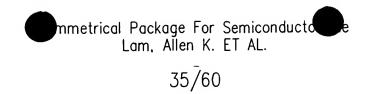


FIG. 7



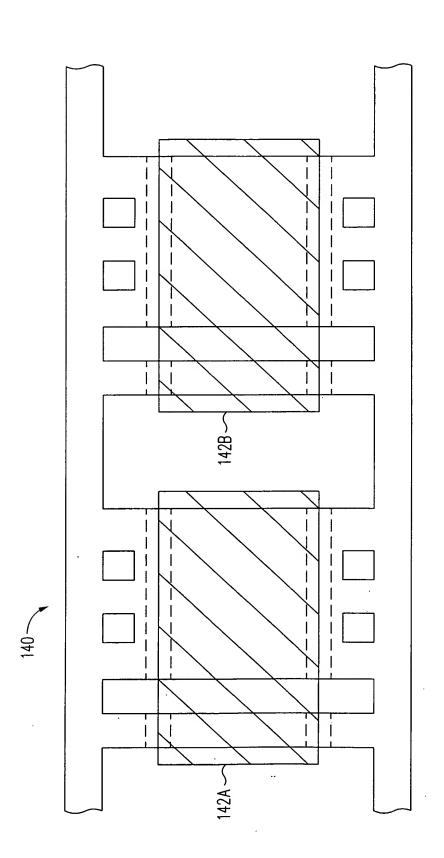


FIG. 70

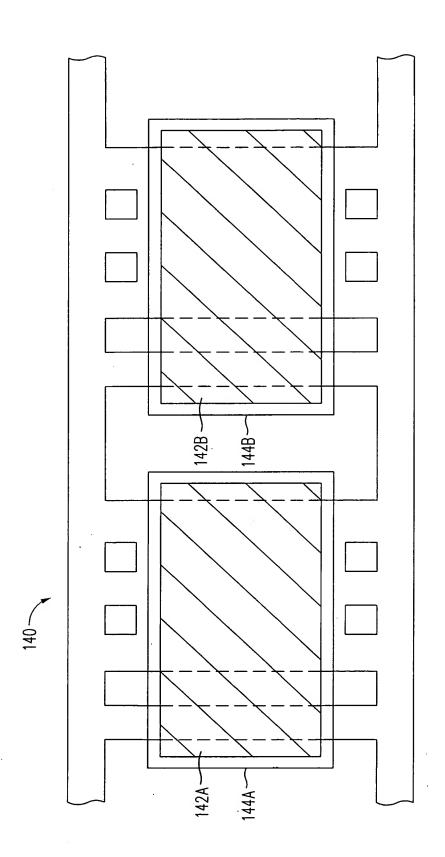


FIG. 71



37/60

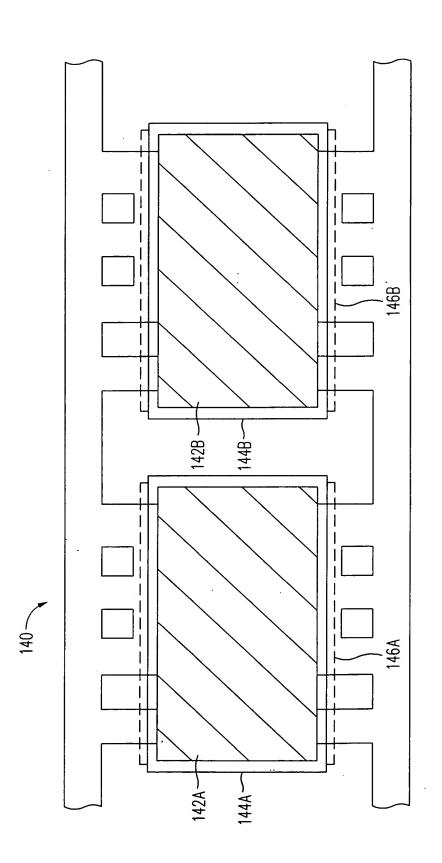
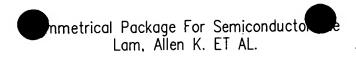
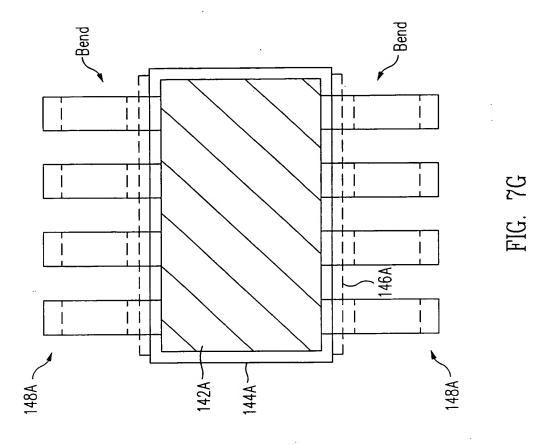
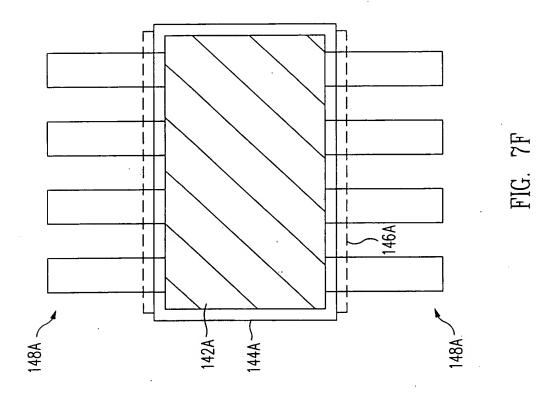


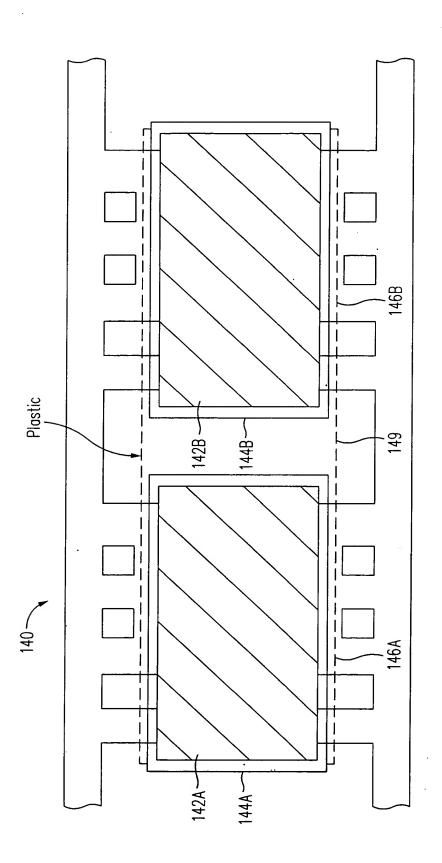
FIG. 71



38/60

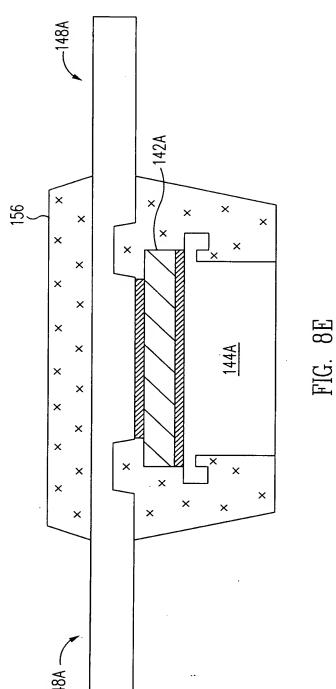




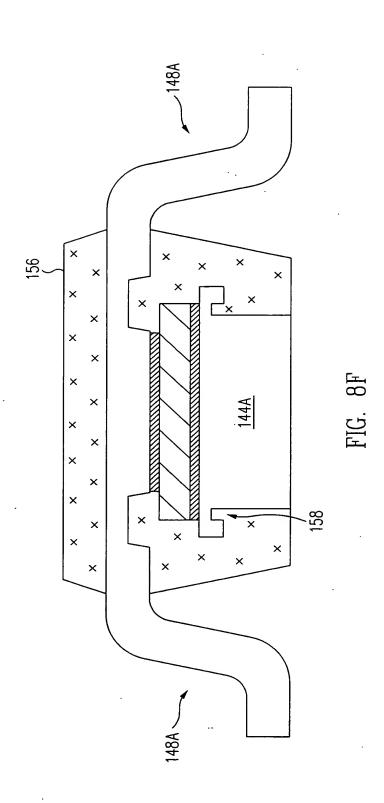


F1G. 71

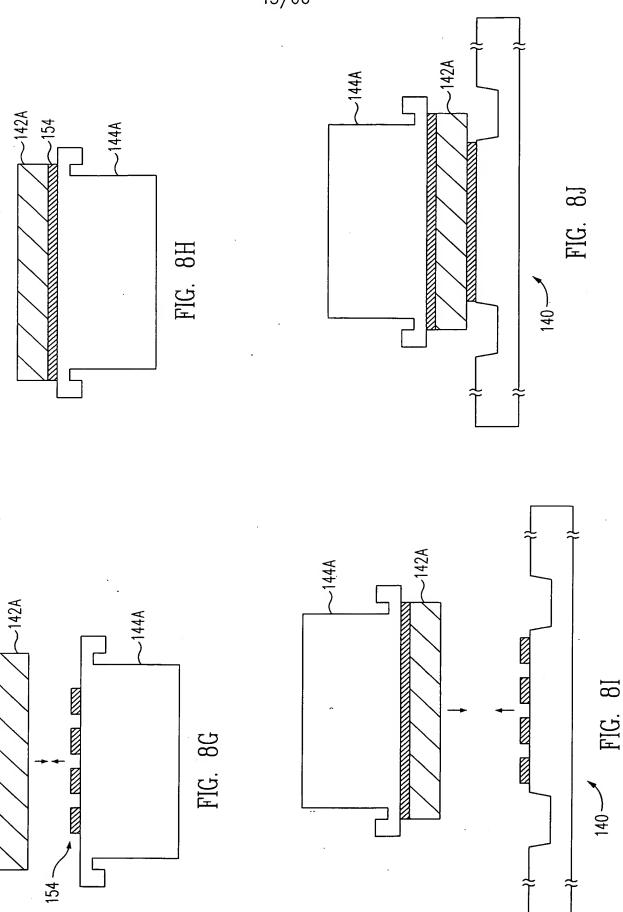
FIG. 8D





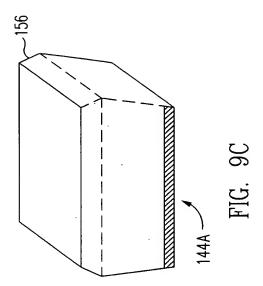


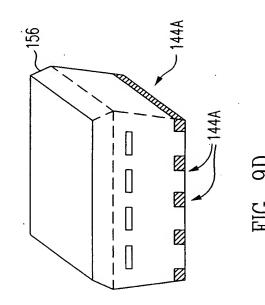
43/60

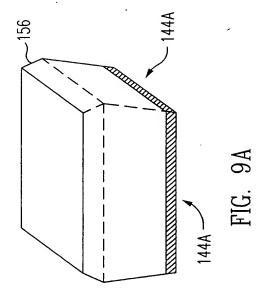




44/60







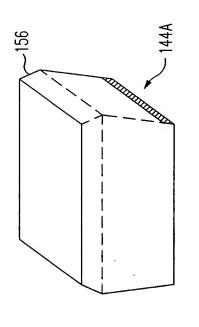
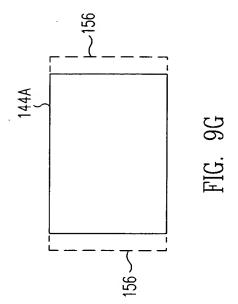
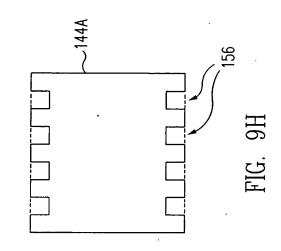
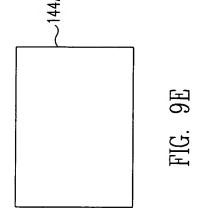


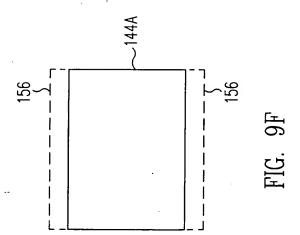
FIG. 9B

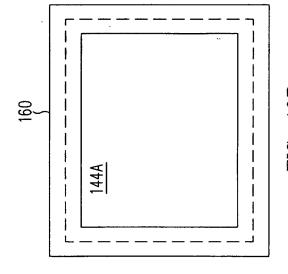


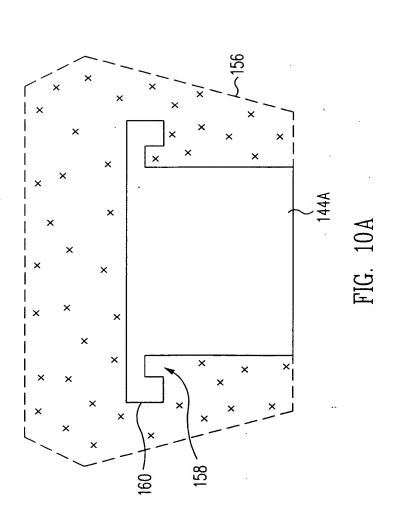




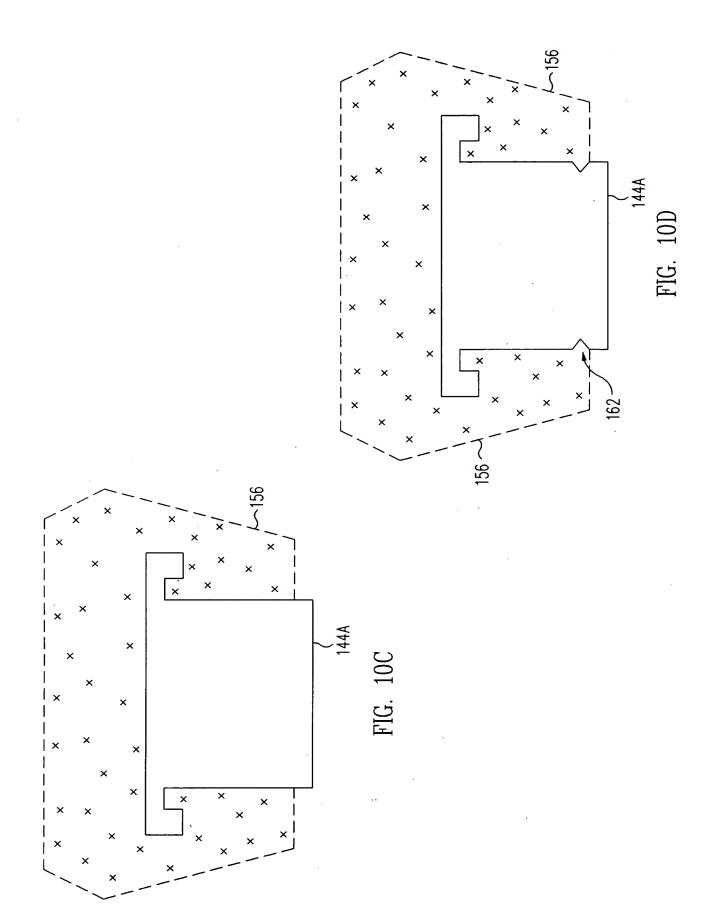


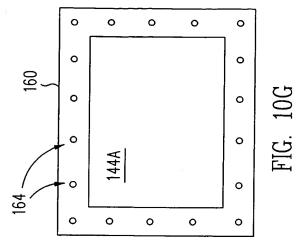


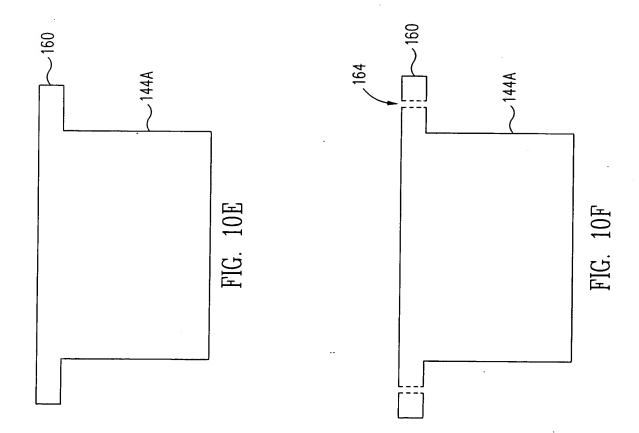


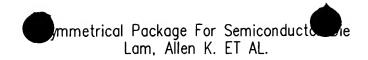


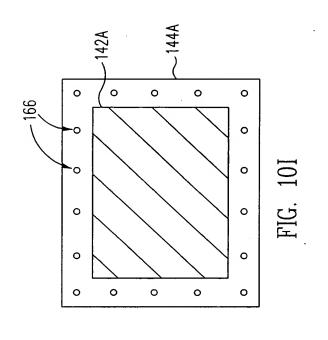
mmetrical Package For Semiconducto. e Lam, Allen K. ET AL.

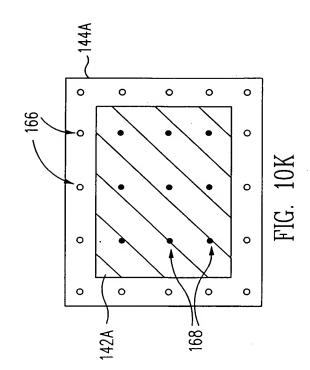


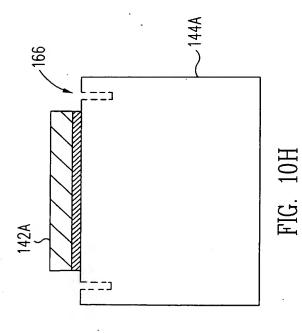


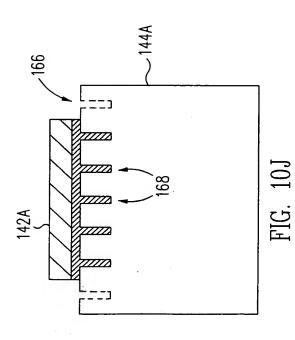


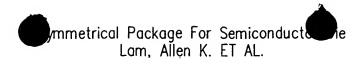


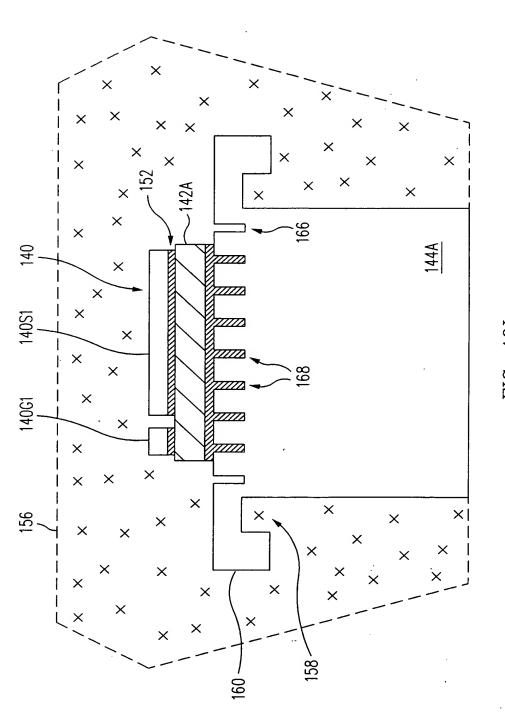












F.IG. 101

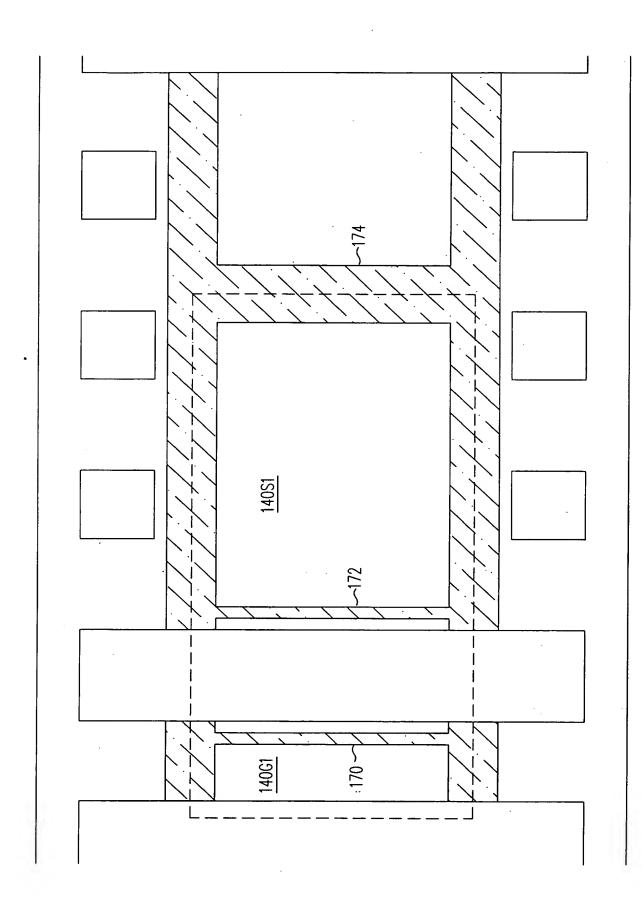
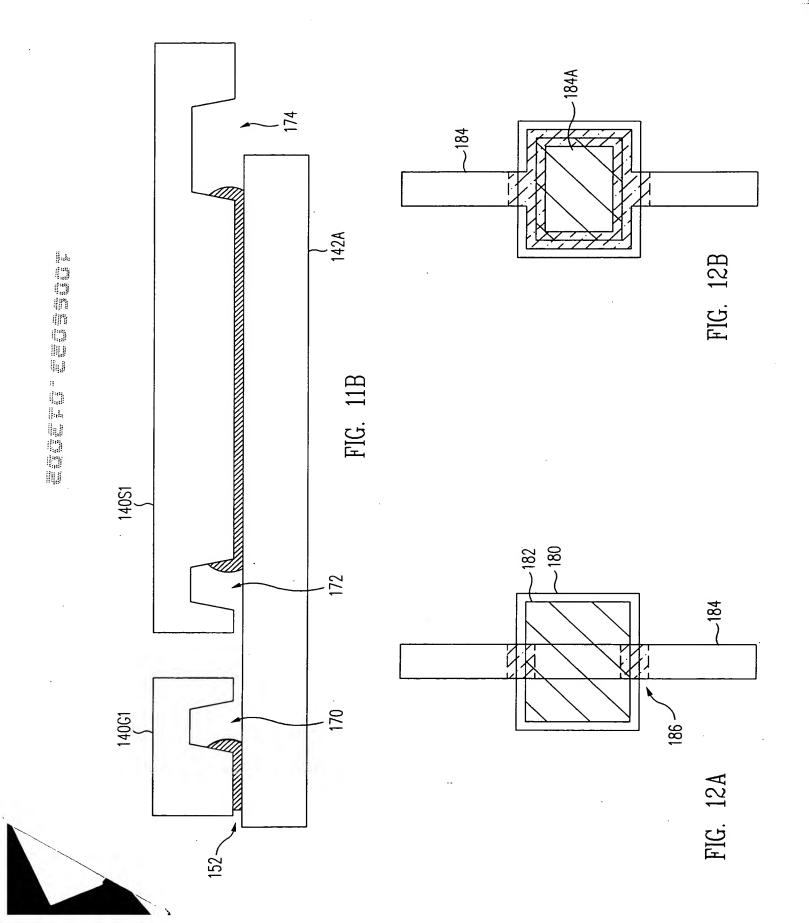


FIG. 11A



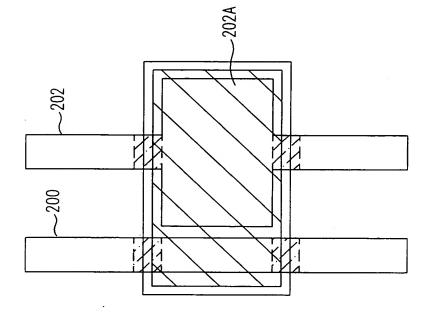


FIG. 12D

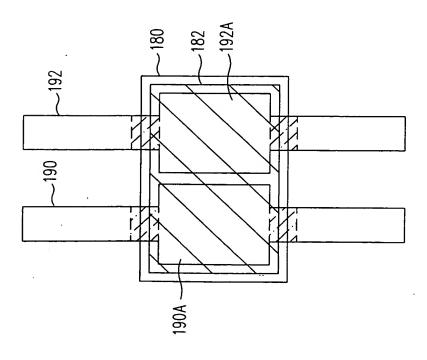


FIG. 12(



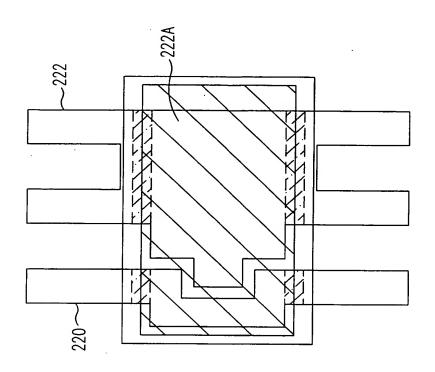


FIG. 12F

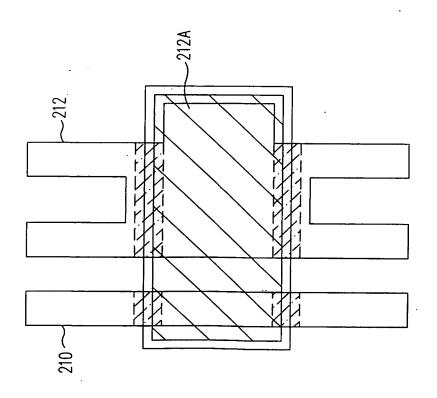


FIG. 121

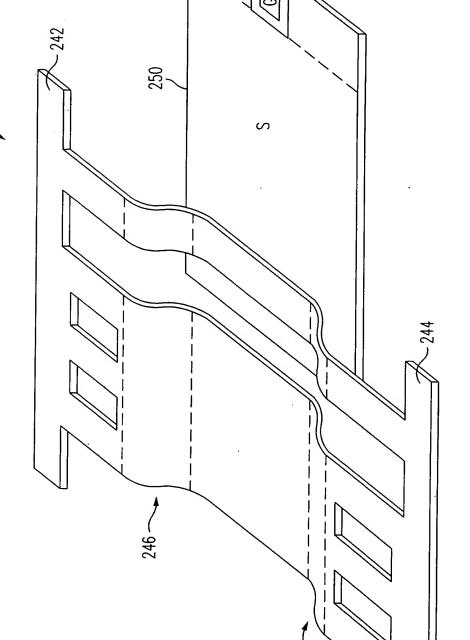


FIG. 13,



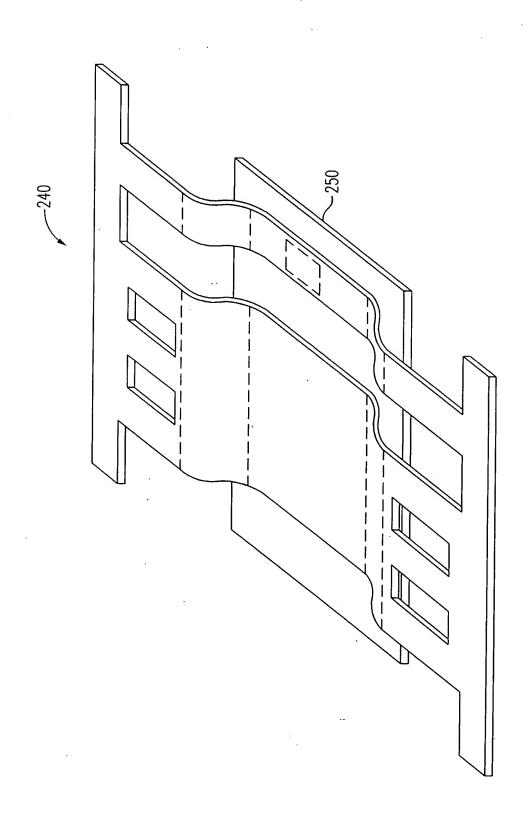
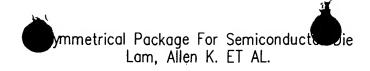
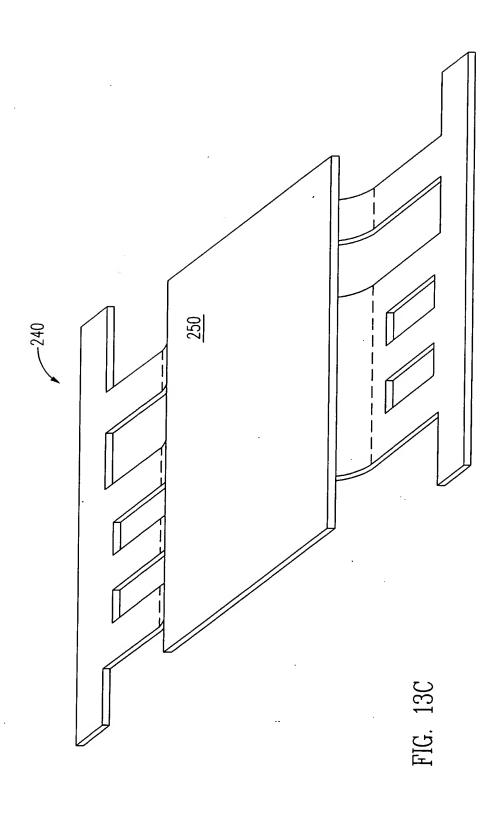


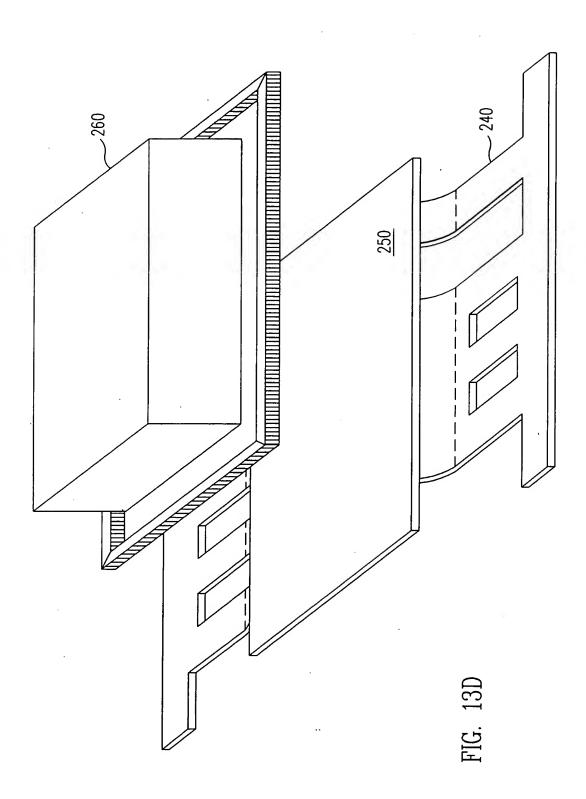
FIG. 13B

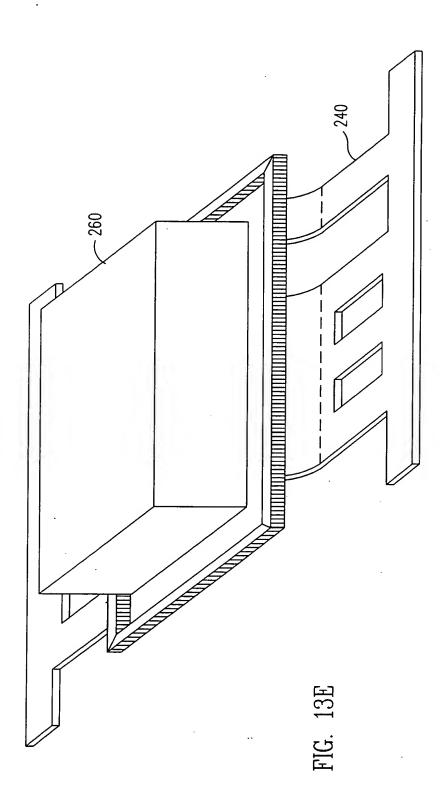




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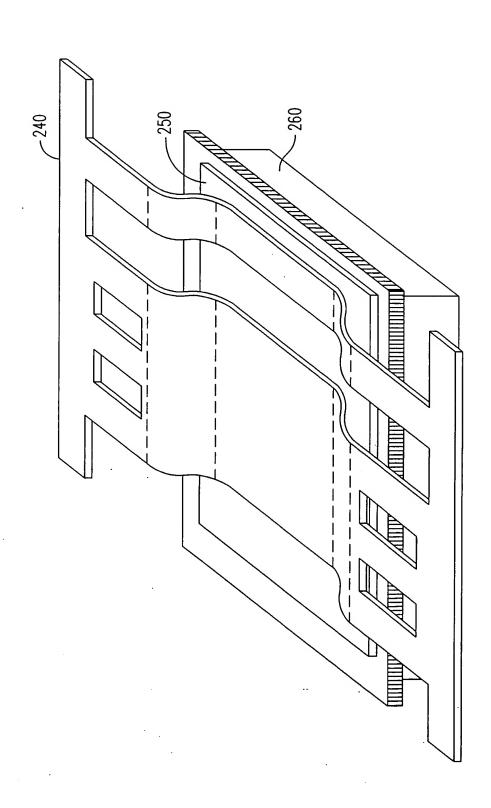


FIG. 13